

06-26-2000



101388939

Tab settings

To the Honorable Commissioner of Patent

Attached original documents or copy thereof.

1. Name of conveying party(ies):
Ikuo Shohji

2. Name and address of receiving party(ies):

Name: **International Business Machines Corporation**

Internal Address:

Street Address: **New Orchard Road**

City: **Armonk** State: **NY** ZIP: **10504**

Additional names(s) of conveying party(ies) Yes No

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other

Execution Date: **5/16/2000**

4. Application number(s) or registration numbers(s):

If this document is being filed together with a new application, the execution date of the application is: **5/16/2000**

A. Patent Application No.(s)

B. Patent No.(s)

JA998233

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **Lawrence R. Fraley**

Internal Address: **IBM Corporation, N50/040-4**

Street Address: **1701 North Street**

City: **Endicott** State: **NY** ZIP: **13760**

6. Total number of applications and patents involved: **1**

7. Total fee (37 CFR 3.41):.....\$ **40.00**

- Enclosed - Any excess or insufficiency should be credited or debited to deposit account
- Authorized to be charged to deposit account

8. Deposit account number:

09-0457

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Lawrence R. Fraley, Reg. No. 26,885

Name of Person Signing

Signature

May 25, 2000

Date

Total number of pages including cover sheet, attachments, and document: **2**

PATENT

REEL: 010868 FRAME: 0801

A S S I G N M E N T

Whereas, I, Ikuo Shohji
5-1-910, Umeda-cho, Mariyama-shi
Shiga-ken, Japan

have invented certain improvements in

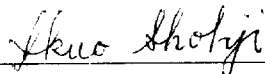
Lead-Free Solder Powe^d Material, Lead-Free Solder Paste And A Method For Preparing
Same

and have executed, respectively, a United States patent application therefor on
5 / 16 / 2000 .

And whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and I hereby agree that IBM may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed at Yasu (at Yasu) , on 5/16/2000 .



Ikuo Shohji